

# Tribocomp<sup>®</sup> PA66 LGF30 TS0 S8 polyamide 66

Tribocomp® PA66 LGF30 TS0 S8, is a 30% long glass fiber reinforced, black, high-flow PA66 compound containing 15% PTFE and having excellent tribological performance. It can easily be processed on most injection molding machines.

Material Status       Commercial: Active         • Africa & Middle East         • Availability         • Asia Pacific         • Europe	<ul> <li>Latin America</li> <li>North America</li> <li>PTFE, 15% Filler by <sup>1</sup></li> </ul>		
	• PTFE, 15% Filler by '		
Filler / Reinforcement • Long Glass Fiber, 30% Filler b Weight		• PTFE, 15% Filler by Weight	
<ul> <li>Abrasion Resistant</li> <li>Heat Stabilized</li> <li>High Flow</li> </ul>	<ul><li>High Friction</li><li>High Temperature</li><li>Low Shrinkage</li></ul>	<ul> <li>High Temperature Strength</li> </ul>	
<ul> <li>Automotive Applications</li> <li>Substantiation</li> <li>Substantiation</li> <li>Automotive Under the Hood</li> <li>Engineering Parts</li> </ul>		<ul><li>Gears</li><li>Industrial Applications</li><li>Power/Other Tools</li></ul>	
RoHS Compliance• RoHS Compliant			
Appearance • Black			
Forms • Pellets			
Processing Method • Compression Molding	<ul> <li>Injection Molding</li> </ul>		
Physical Dry	Conditioned Unit	Test method	
Density 1.50	g/cm³	ISO 1183	
Molding Shrinkage - Flow 0.40	%	ISO 294-4	
Water Absorption 1.4 (Equilibrium, 23°C, 50% RH)	%	ISO 62	
Mechanical Dry	Conditioned Unit	Test method	
Tensile Modulus		ISO 527-1	
23°C 10500	8000 MPa		
90°C 6600	MPa		
Tensile Stress		ISO 527-2	
Break, 23°C 195	145 MPa		
Break, 90°C 125	MPa		
Tensile Strain		ISO 527-2	
Yield, 23°C 3.0	%		
Break, 23°C	2.0 %		
Flexural Modulus (23°C)10200	MPa	ISO 178	
Flexural Stress (23°C) 285	MPa	ISO 178	

Mechanical	Dry	Conditioned Unit	Test method
Coefficient of Friction			ASTM D3702
Dynamic	0.23		
Static	0.18		
Wear Factor	13.0		ASTM D3702
Impact	Dry	Conditioned Unit	Test method
Charpy Notched Impact Strength (23°C)	20	kJ/m²	ISO 179
Charpy Unnotched Impact Strength (23°C)	70	kJ/m²	ISO 179
Thermal	Dry	Conditioned Unit	Test method
Deflection Temperature Under Load			
0.45 MPa, Unannealed	262	°C	ISO 75-2/B
1.8 MPa, Unannealed	258	°C	ISO 75-2/A
Thermal Conductivity	0.29	W/m/K	ISO 22007
Coefficient of Linear Thermal Expansion	2.9E-5	cm/cm/°C	ISO 11359-2
Electrical	Dry	Conditioned Unit	Test method
Electric Strength (2.00 mm)	35	kV/mm	IEC 60243-1
Comparative Tracking Index	500	V	IEC 60112
Surface Resistivity	1.0E+12	ohms/sq	ASTM D257

#### Additional Information

Dry

The value listed as Molding Shrinkage ISO 294-4, was tested in accordance with S.O.P. methods.

Dry Unit	
80 to 100 °C	
4.0 hr	
0.10 %	
290 to 300 °C	
300 °C	
300 °C	
300 °C	
< 300 °C	
80 to 120 °C	
-	80 to 100 °C 4.0 hr 0.10 % 290 to 300 °C 300 °C 300 °C 300 °C < 300 °C

#### **Injection Notes**

Pre-drying -- Since polyamides are hygroscopic materials as well as sensitive to moisture during processing, this product should always be pre-dried.

Regrind -- Regrind of highly filled thermoplastic materials, such as this material, should only be recycled with special care. The regrind content must never exceed 15%, and only regrind of optimum quality should be used. In any case, part properties should be checked.

## Notes

Typical properties: these are not to be construed as specifications.

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